ON Semiconductor

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MOSFET - Power, N-Channel, SUPERFET III, FRFET

650 V, 36 A, 95 mΩ

NVHL095N65S3F

Description

SUPERFET III MOSFET is ON Semiconductor's brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This advanced technology is tailored to minimize conduction loss, provide superior switching performance, and withstand extreme dv/dt rate.

Consequently, SUPERFET III MOSFET is very suitable for the various power system for miniaturization and higher efficiency.

SUPERFET III FRFET MOSFET's optimized reverse recovery performance of body diode can remove additional component and improve system reliability.

Features

- 700 V @ $T_J = 150$ °C
- Typ. $R_{DS(on)} = 78 \text{ m}\Omega$
- Ultra Low Gate Charge (Typ. $Q_g = 65 \text{ nC}$)
- Low Effective Output Capacitance (Typ. Coss(eff.) = 597 pF)
- 100% Avalanche Tested
- AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen-Free/BFR-Free and are RoHS Compliant

Applications

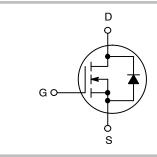
- Automotive On Board Charger HEV-EV
- Automotive DC/DC Converter HEV-EV



ON Semiconductor®

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V _{DSS}	R _{DS(ON)} MAX	I _D MAX
650 V	95 mΩ @ 10 V	36 A





TO-247 long leads CASE 340CX

DIAGRAM (

MARKING

\$Y&Z&3&K NVHL095 N65S3F

\$Y = ON Semiconductor Logo &Z = Assembly Plant Code &3 = Data Code (Year & Week)

&K = Lot

NVHL095N65S3F = Specific Device Code

ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

ABSOLUTE MAXIMUM RATINGS ($T_C = 25^{\circ}C$, Unless otherwise noted)

Symbol	Parameter	Value	Unit	
V _{DSS}	Drain to Source Voltage			V
V _{GSS}	Gate to Source Voltage	- DC		V
		- AC (f > 1 Hz)	±30	
I _D	Drain Current – Continuous (T _C = 25°C)		36	Α
		- Continuous (T _C = 100°C)	22.8	
I _{DM}	Drain Current	- Pulsed (Note 1)	90	Α
E _{AS}	Single Pulsed Avalanche Energy (Note 2)	440	mJ	
I _{AS}	Avalanche Current (Note 2)	,		Α
E _{AR}	Repetitive Avalanche Energy (Note 1)			mJ
dv/dt	MOSFET dv/dt		100	V/ns
	Peak Diode Recovery dv/dt (Note 3)	e Recovery dv/dt (Note 3)		
P_{D}	Power Dissipation	(T _C = 25°C)	272	W
		- Derate Above 25°C	2.176	W/°C
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150	°C
TL	Maximum Lead Temperature for Soldering, 1/8"	300	°C	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected. 1. Repetitive rating: pulse–width limited by maximum junction temperature. 2. $I_{AS} = 4.6 \text{ A}$, $R_{G} = 25 \Omega$, starting $T_{J} = 25^{\circ}\text{C}$. 3. $I_{SD} \le 18 \text{ A}$, $di/dt \le 200 \text{ A/µs}$, $V_{DD} \le 400 \text{ V}$, starting $T_{J} = 25^{\circ}\text{C}$.

THERMAL CHARACTERISTICS

Symbol	Parameter	Value	Unit
$R_{ heta JC}$	Thermal Resistance, Junction to Case, Max.	0.46	°C/W
$R_{ heta JA}$	R _{0JA} Thermal Resistance, Junction to Ambient, Max.		

PACKAGE MARKING AND ORDERING INFORMATION

Part Number	Top Marking	Package	Packing Method	Reel Size	Tape Width	Quantity
NVHL095N65S3F	NVHL095N65S3F	TO-247	Tube	N/A	N/A	30 Units

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
OFF CHARACTERISTICS						•
Drain to Source Breakdown Voltage	BV _{DSS}	$V_{GS} = 0 \text{ V, } I_D = 1 \text{ mA, } T_J = 25^{\circ}\text{C}$	650			V
		V _{GS} = 0 V, I _D = 10 mA, T _J = 150°C	700			V
Breakdown Voltage Temperature Coefficient	$\Delta BV_{DSS}/\Delta T_{J}$	I _D = 15 mA, Referenced to 25°C		640		mV/°C
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 650 V, V _{GS} = 0 V			10	μΑ
		V _{DS} = 520 V, T _C = 125°C		12		
Gate to Body Leakage Current	I _{GSS}	V _{GS} = ±30 V, V _{DS} = 0 V			±100	nA
ON CHARACTERISTICS				1	•	
Gate Threshold Voltage	V _{GS(th)}	$V_{GS} = V_{DS}, I_D = 0.86 \text{ mA}$	3.0		5.0	V
Threshold Temperature Coefficient	$\Delta V_{GS(th)}/\Delta T_{J}$	$V_{GS} = V_{DS}, I_D = 0.86 \text{ mA}$		-7		mV/°C
Static Drain to Source On Resistance	R _{DS(on)}	V _{GS} = 10 V, I _D = 18 A		78	95	mΩ
Forward Transconductance	9FS	V _{DS} = 20 V, I _D = 18 A		19		S
DYNAMIC CHARACTERISTICS			1	-1	I	<u>.</u> L
Input Capacitance	C _{iss}			3020		pF
Output Capacitance	C _{oss}	V _{DS} = 400 V, V _{GS} = 0 V, f = 1 MHz		61		1
Reverse Transfer Capacitance	C _{rss}			7.0		-
Effective Output Capacitance	C _{oss(eff.)}	V _{DS} = 0 V to 400 V, V _{GS} = 0 V		597		pF
Energy Related Output Capacitance	C _{oss(er.)}	V _{DS} = 0 V to 400 V, V _{GS} = 0 V		107		pF
Total Gate Charge at 10V	Q _{g(tot)}			66		nC
Threshold Gate Charge	Q _{g(th)}	V _{GS} = 10 V, V _{DS} = 400 V, I _D = 18 A		13		1
Gate to Source Gate Charge	Q _{gs}	(Note 4)		22		1
Gate to Drain "Miller" Charge	Q _{gd}			26		1
Equivalent Series Resistance	ESR	f = 1 MHz		2.4		Ω
SWITCHING CHARACTERISTICS				ı		
Turn-On Delay Time	t _{d(on)}			26		ns
Turn-On Rise Time	t _r	V_{GS} = 10 V, V_{DD} = 400 V, I_{D} = 18 A, R_{g} = 2.2 Ω		26		ns
Turn-Off Delay Time	t _{d(off)}	I _D = 18 A, R _g = 2.2 Ω (Note 4)		62		ns
Turn-Off Fall Time	t _f	,		4.0		ns
SOURCE-DRAIN DIODE CHARACTER	ISTICS		·L	L	l	<u>.l</u>
Maximum Continuous Source to Drain Diode Forward Current	I _S	V _{GS} = 0 V			36	А
Maximum Pulsed Source to Drain Diode Forward Current	I _{SM}	V _{GS} = 0 V			90	А
Source to Drain Diode Forward Voltage	V _{SD}	V _{GS} = 0 V, I _{SD} = 18 A			1.3	V
Reverse Recovery Time	t _{rr}			97		ns
Charge Time	t _a	V _{GS} = 0 V, dI _F /dt = 100 A/μs,		78		1
Discharge Time	t _b	$I_{SD} = 18 \text{ A}$		19		1
Reverse Recovery Charge	Q _{rr}			349		nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

^{4.} Essentially independent of operating temperature typical characteristics.

TYPICAL CHARACTERISTICS

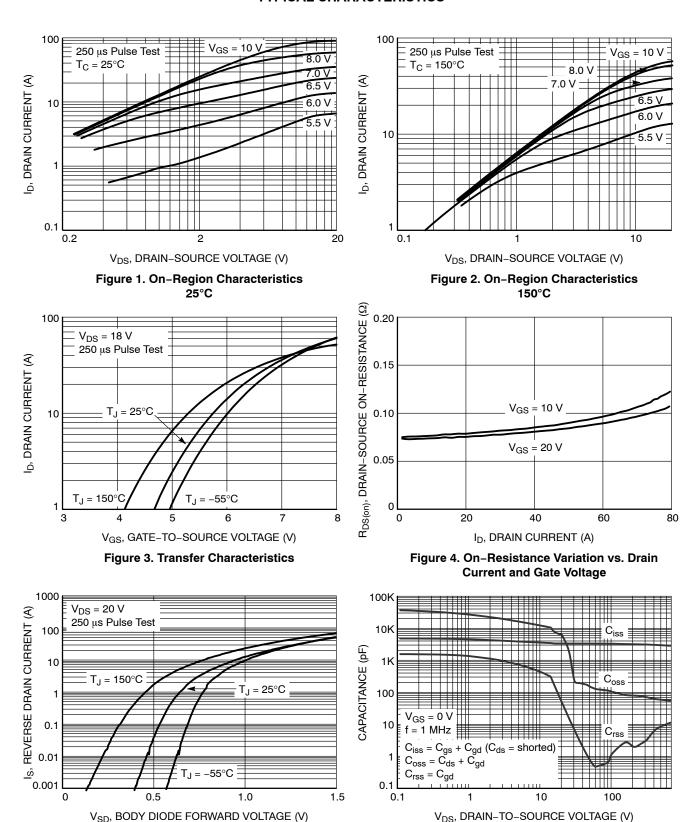
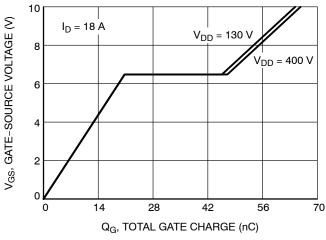


Figure 6. Capacitance Characteristics

Figure 5. Body Diode Forward Voltage

Variation vs. Source Current and Temperature

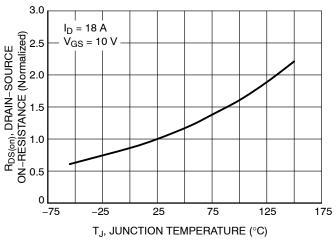
TYPICAL CHARACTERISTICS



1.2 V_{GS} = 0 V V_D = 10 mA 1.1 V_{SO} = 0 V V_D = 10 mA 1.1 V_S = 0 V V_D = 10 mA 1.1 V_S = 0 V V_D = 10 mA V_S = 0 V V_D = 10 mA V_S = 0 V V_D = 10 mA V_S = 0 V V_S = 0 V V_D = 10 mA V_D = 10

Figure 7. Gate Charge Characteristics

Figure 8. Breakdown Voltage Variation vs. Temperature



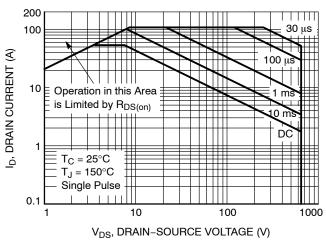
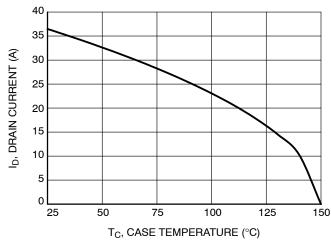


Figure 9. On-Resistance Variation vs. Temperature

Figure 10. Maximum Safe Operating Area



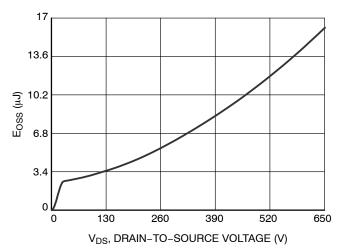
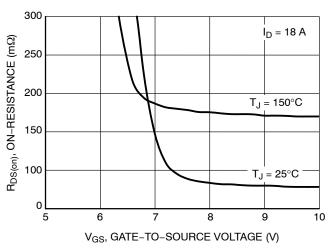


Figure 11. Maximum Drain Current vs. Case Temperature

Figure 12. E_{OSS} vs. Drain-to-Source Voltage

TYPICAL CHARACTERISTICS



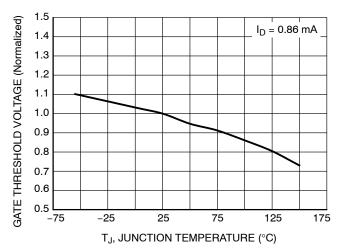


Figure 13. R_{DS(on)} vs. Gate Voltage

Figure 14. Normalized Gate Threshold Voltage vs. Temperature

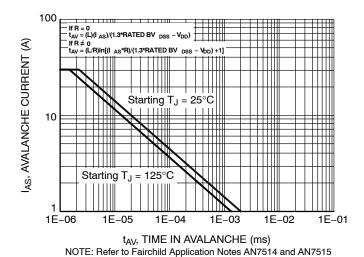


Figure 15. Unclamped Inductive Switching Capability

TYPICAL CHARACTERISTICS

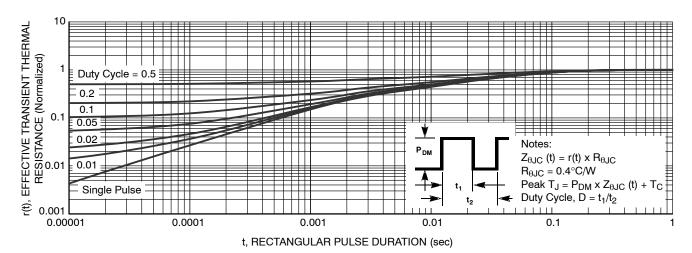


Figure 16. Transient Thermal Response

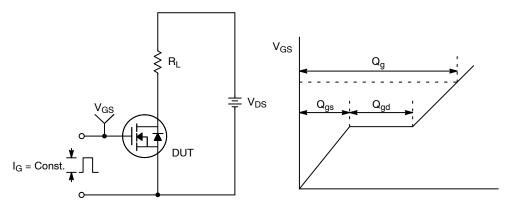


Figure 17. Gate Charge Test Circuit & Waveform

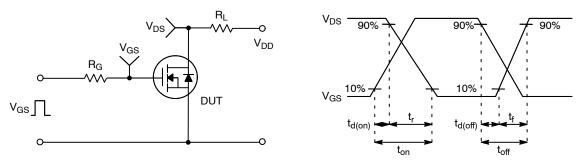


Figure 18. Resistive Switching Test Circuit & Waveforms

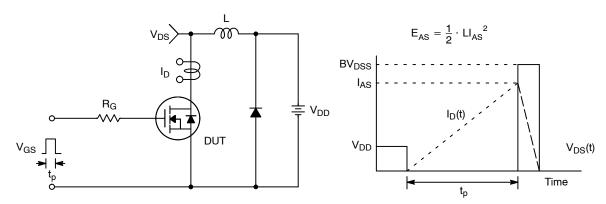
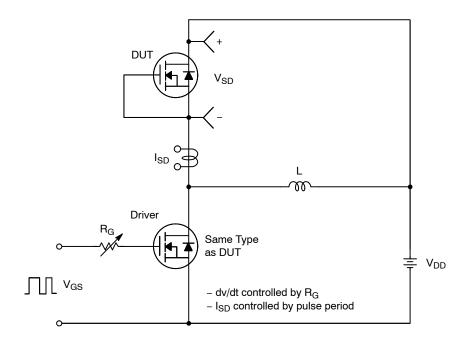
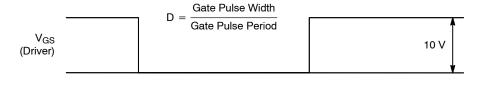
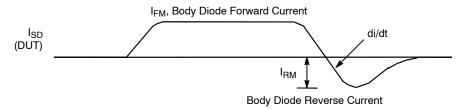


Figure 19. Unclamped Inductive Switching Test Circuit & Waveforms







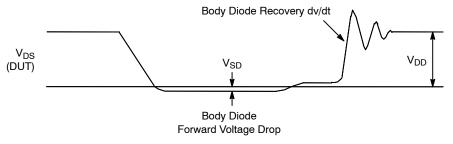
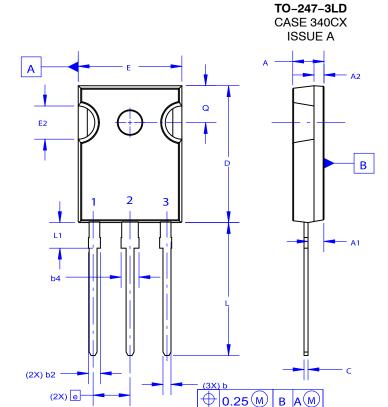


Figure 20. Peak Diode Recovery dv/dt Test Circuit & Waveforms

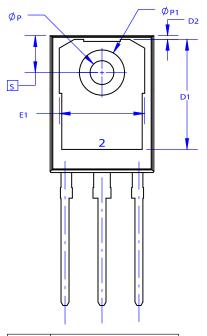
PACKAGE DIMENSIONS



NOTES: UNLESS OTHERWISE SPECIFIED.

- A. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

 B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DRAWING CONFORMS TO ASME Y14.5 2009.
- D. DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED BY L1.
- E. LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY L1.



DIM	MILLIMETERS					
DIM	MIN	NOM	MAX			
Α	4.58	4.70	4.82			
A1	2.20	2.40	2.60			
A2	1.40	1.50	1.60			
D	20.32	20.57	20.82			
Е	15.37	15.62	15.87			
E2	4.96	5.08	5.20			
е	?	5.56	~			
L	19.75	20.00	20.25			
L1	3.69	3.81	3.93			
ØР	3.51	3.58	3.65			
Q	5.34	5.46	5.58			
S	5.34	5.46	5.58			
b	1.17	1.26	1.35			
b2	1.53	1.65	1.77			
b4	2.42	2.54	2.66			
С	0.51	0.61	0.71			
D1	13.08	?	~			
D2	0.51	0.93	1.35			
E1	12.81	~	?			
ØP1	6.60	6.80	7.00			

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